

OM SENI

H5VL10B

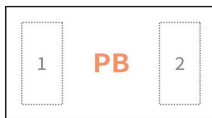
Bi-directional 5V Low Capacitance ESD

DFN1006-2L Plastic-Encapsulate ESD Protection Diodes**Features**

- Low leakage current
- Low clamping voltage
- IEC 61000-4-2 (ESD Air): $\pm 25\text{kV}$
- IEC 61000-4-2 (ESD Contact): $\pm 25\text{kV}$
- IEC 61000-4-5 (Lightning 8/20 μs): 5A

Applications

- Cellular Handsets and Accessories
- Notebooks and Handhelds
- Personal Digital Assistants
- Keypads, Side Keys, LCD Displays
- Audio Players, Peripherals
- Portable Instrumentation

Function Diagram

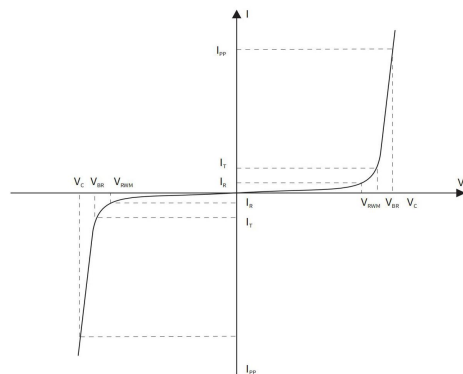
Reverse Working Voltage
5.0 V Max.
Low capacitance
15pF(Typ.)

**Maximum Ratings** (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V _{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	± 25	KV
		ESD per IEC 61000-4-2(Contact)	± 25	KV
P _{PP}	Peak Pulse Power	tp = 8/20 μs	50	W
I _{PP}	Rated Peak Pulse Current	tp = 8/20 μs	5.0	A
T _J	Operating JunctionTemperature Range	—	-55 to +125	°C
T _{STG}	Operating JunctionTemperature Range	—	-55 to +125	°C

Electrical Parameter

SYMBOL	PARAMETER
V _C	Clamping Voltage @ I _{PP}
V _{BR}	Breakdown Voltage @ I _T
I _{PP}	Peak Pulse Current
I _T	Test Current
I _R	Reverse Leakage Current @ VRWM
V _{RWM}	Peak Reverse Working Voltage
P _{PP}	Peak Pulse Power Dissipation
C _J	Junction Capacitance @ V _R =0V,f=1MHz
I _F	Forward Current
V _F	Forward Voltage @I _F

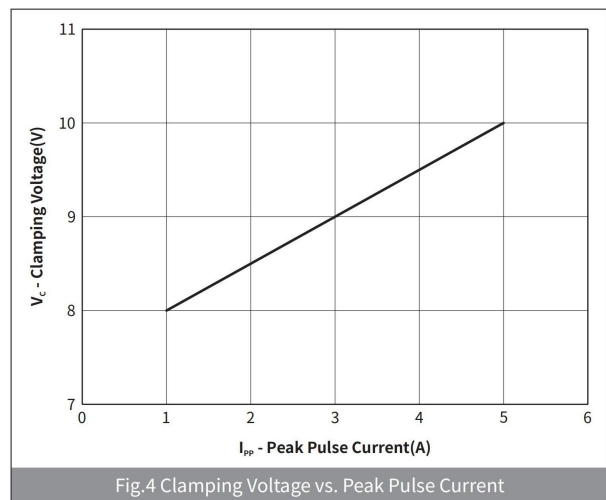
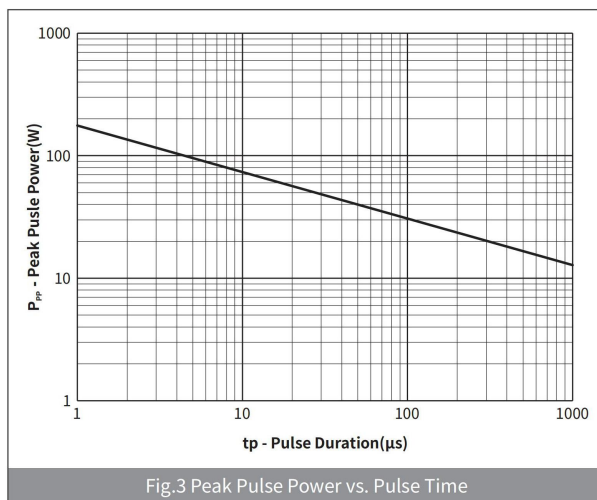
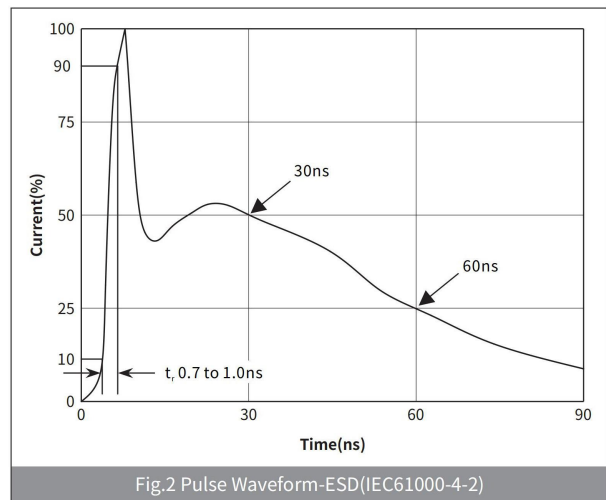
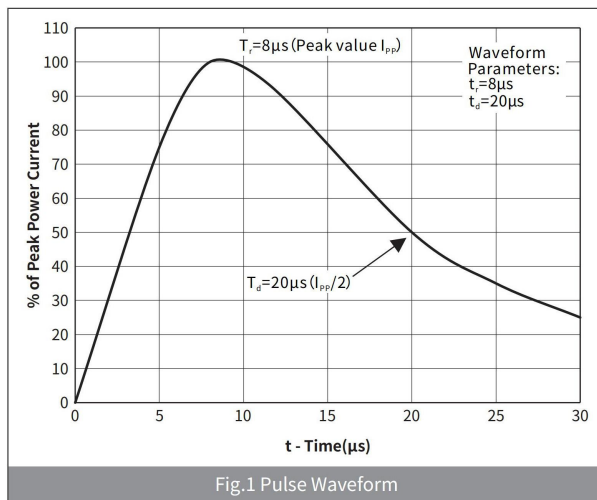


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Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	V_{RWM}	$T_a=25^\circ\text{C}$	—	—	5.0	V
Breakdown Voltage	V_{BR}	$I_T=1.0\text{mA}, T_a=25^\circ\text{C}$	5.6	6.5	8.0	V
Reverse Leakage Current	I_R	$V_{RWM}=5.0\text{V}; T_a=25^\circ\text{C}$	—	—	0.1	μA
Clamping Voltage	V_C	$I_{PP}=1.0\text{A}, t_p=8/20\mu\text{s}$	—	—	8.0	V
		$I_{PP}=5.0\text{A}, t_p=8/20\mu\text{s}$	—	—	10.0	
Junction Capacitance	C_J	$V_R=0\text{V}, f=1\text{MHz}$	—	15	18	pF

Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



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Ordering Information

PREFERRED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
	DFN1006-2L	1.00×0.60×0.37	7" REEL	10,000

Recommended Soldering Conditions



Package Outline Dimensions (DFN1006-2L)



Suggested Pad Layout

